## Device Material Content

<table>
<thead>
<tr>
<th>Package: 672 fpBGA</th>
<th>Package Code: FN672</th>
</tr>
</thead>
<tbody>
<tr>
<td>Total Device Weight</td>
<td>3.30 Grams</td>
</tr>
<tr>
<td>Products: LAE3</td>
<td></td>
</tr>
<tr>
<td>Size (mm): 27 x 27</td>
<td></td>
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<tr>
<td>Lead pitch (mm): 1.0</td>
<td></td>
</tr>
<tr>
<td>MSL: 3</td>
<td></td>
</tr>
<tr>
<td>Rework max (ºC): 250</td>
<td></td>
</tr>
</tbody>
</table>

### Die
- **Die**: 1.48% 0.0489
- **Silicon chip**: 1.48% 0.0489
- **Die size**: 8.11 x 8.34 mm

### Mold Compound
- **Mold Compound**: 36.73% 1.2119
- **Epoxy Resin**: 1.84% 0.0606
- **Phenol Resin**: 1.84% 0.0606
- **Carbon Black**: 0.07% 0.0024
- **Silica**: 32.24% 1.0641
- **Others**: 0.73% 0.0242

### D/A Epoxy
- **D/A Epoxy**: 0.21% 0.0069
- **Silver**: 0.17% 0.00550
- **Silver (Cu)**: 0.04% 0.00137

### Wire
- **Wire**: 0.60% 0.0198
- **Gold (Au)**: 0.59% 0.0195

### Solder Balls
- **Solder Balls**: 19.89% 0.6563
- **Tin (Sn)**: 19.19% 0.6333
- **Silver (Ag)**: 0.60% 0.0197
- **Copper (Cu)**: 0.10% 0.0033

### Substrate
- **Substrate**: 24.23% 0.8002
- **BT Resin**: 7.76% 0.2561
- **Glass fiber**: 16.49% 0.5441

### Foil
- **Foil**: 11.03% 0.3639
- **Copper**: 9.04% 0.2984
- **Nickel plating**: 1.66% 0.0549
- **Gold plating**: 0.32% 0.0106

### Soldier Mask
- **Soldier Mask**: 5.82% 0.1922
- **Quartz**: 3.27% 0.1080
- **3-methoxy-3-methylbutylacetate**: 0.93% 0.0308
- **Barium Sulfate**: 1.28% 0.0423
- **Talc (containing no asbestiform fibers)**: 0.17% 0.0058
- **Trade secret ingredients**: 0.16% 0.0054

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The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible. Constituent substances and proportions in epoxy materials are before curing. The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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